

Electronic Patent Application Fee Transmittal

Application Number:	10718192				
Filing Date:	20-Nov-2003				
Title of Invention:	HEAT SPREADER BALL GRID ARRAY (HSBGA) DESIGN FOR LOW-K INTEGRATED CIRCUITS (IC)				
First Named Inventor/Applicant Name:	Yian-Liang Kuo				
Filer:	Daniel R. McClure/Hui Chin Barnhill				
Attorney Docket Number:	TS03-336				
Filed as Large Entity					
Utility Filing Fees					
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:					
Pages:					
Claims:					
Miscellaneous-Filing:					
Petition:					
Patent-Appeals-and-Interference:					
Post-Allowance-and-Post-Issuance:					
Extension-of-Time:					

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180